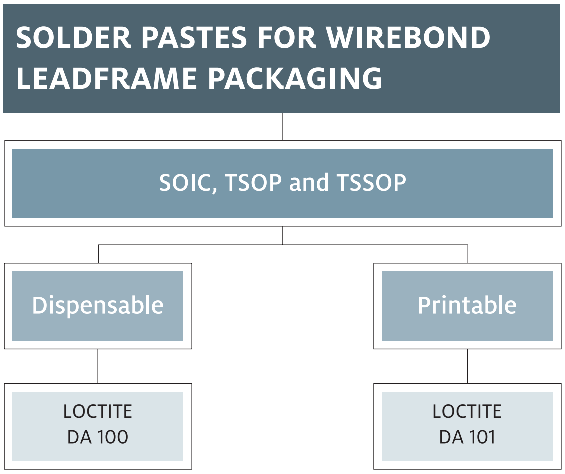
LOCTITE®

Henkel Solutions for Leadframe Packaging
Solder Pastes


SOLDER PASTES FOR WIREBOND LEADFRAME PACKAGING

SOIC, TSOP and TSSOP

Dispensable

Printable

LOCTITE DA 100

LOCTITE DA 101

SOLDER PASTES

PRODUCTD	ESCRIPTION	KEY ATTRIBUTES	ALLOY	PARTICLE SIZE DISTRIBUTION	VISCOSITY AT 25˚C	REFLOW ATMOSPHERE	IPC J-STD 004B CLASSIFICATION	SHELF LIFE
Dispensable								
LOCTITE DA 100	Halide-free, no-clean solder paste with Pb-free and high-Pb options	• Low color residues resistant to charring in reflow • Very low voiding • Vacuum-mixed for reliable dispensing performance • Excellent dispense and pause time capability • Robust flux effective over a wide range of reflow profiles	2.5S 92A	Type 3, 4	300,000 – 310,000 at 5 rpm	Forming gas	ROL0	12 months up to -18°C
Printable								
LOCTITE DA 101	Halide-free, no-clean solder paste with Pb-free and high-Pb options	• Low color residues resistant to charring in reflow • Very low voiding • Robust flux effective over a wide range of reflow profiles	2.5S 92A 95A	Type 3	600,000 at 5 rpm	Forming gas	ROL0	6 months at 0°C – 10°C

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